Hyeongju Jeon

## Research Interests

Physics-based finite element modeling of hybrid bonding process

CFD-based analysis of slurry flow behavior in chemical mechanical planarization (CMP) process

## Publications

## Conferences

“Analysis of interface interaction and residual stress considering plasticity and creep in hybrid bonding”, Korean Society for Technology of Plasticity and Materials Processing (2025 KSTP spring meeting), Changwon, Republic of Korea, May 22-23, 2025

“Finite element based computational bonding model for evaluating the reliability of hybrid bonding process”, The Korean Microelectronics And Packaging Society (2025 KMEPS spring meeting), Songdo, Republic of Korea, April 2-4, 2025

## Achievements & Awards

Best poster award, The Korean Microelectronics And Packaging Society (2025 KMEPS spring meeting), Songdo, Republic of Korea, April 2-4, 2025